

Homework 4 Spring 2019 TA: Abdullah Al-Obaidi

Notes:

- This is a short assignment and will only be worth 50 points
- There are multiple correct solutions to Problems 5 & 6

Problem 1:

For the 248 nm UV machine, the total amount of wafers that can be made its lifetime:

$$N_w = 80 * 24 * 365 * \frac{4}{10} = 280,320 \text{ wafers}$$

$$\text{Cost per wafer: } C_w = \frac{10M}{N_w} = \$35.67$$

$$\text{Number of chips per wafer: } N_c = \frac{A_w}{A_{chip}} = \frac{150^2 \pi}{50} = 1413$$

$$\text{Cost per chip: } C_c = \frac{35.67}{1413} = \$0.025$$

For the 193nm UV machine:

$$\text{Wafers per lifetime: } N_{w2} = 70080$$

$$\text{Cost per wafer: } C_{w2} = \$570.78$$

$$\text{Chips per wafer: } N_{c2} = 1413 * \left(\frac{90}{50}\right)^2 = 4578$$

$$\left(\frac{90}{50}\right)^2 \text{ is the resolution difference}$$

$$\text{Cost per chip: } C_{c2} = \$0.125$$

$$\text{Cost difference } C_\Delta = 0.125 - 0.025 = \$0.1/\text{chip}$$

Problem 2:

The dielectric constant of $\text{SiO}_2 = K_s = 3.9$

The dielectric constant of $\text{HfO}_2 = K_H = 25$

Any K_H between 15 – 25 is accepted

$$\rightarrow \text{Thickness of HfO}_2: t_{\text{HfO}_2} = \frac{25}{3.9} * t_{\text{SiO}_2} = 12.82 \text{ nm}$$

Problem 3:

Resistivity of Aluminum = $2.8 * 10^{-8} \Omega * m$

Resistance of the interconnect $R_{Al} = \frac{\rho l}{wt} \rightarrow t = \frac{\rho l}{wR} = \frac{2.8 * 10^{-8} * 250 * 10^{-6}}{3 * 10^{-6} * 25} = 93.3 * 10^{-9} m = 93.3 nm$

Sheet resistance = $\frac{\rho}{t} = \frac{2.8 * 10^{-8}}{93.3 * 10^{-9}} = 0.3 \Omega/\blacksquare$

Problem 4:

Resistivity of Copper = $1.7 * 10^{-8} \Omega * m$

$$R_{Al} = \frac{\rho l}{wt} \rightarrow l = \frac{Rwt}{\rho} = \frac{3 * 10^{-6} * 25 * 93.3 * 10^{-9}}{1.7 * 10^{-8}} = 412 \mu m$$

Problem 5:

Poly 1: $7.7 \Omega/\blacksquare$

P+: $7.5 \Omega/\blacksquare$

For 10k Ohms

Poly1: $\frac{5,000}{7.7} = 649.4 \blacksquare's$

P+: $\frac{5,000}{7.5} = 666.7 \blacksquare's$

There are a lot of different ways to create the serpentine layout, depending on how many rows you want to make, but it will take approximately 2.3x the area for the P+ resistor. The main reason for this is that a P+ \blacksquare is 0.3×0.3 microns while a Poly \blacksquare is 0.2×0.2 microns

Problem 6:

Code for 4 bit inverter:

Ln#	
1	module inverter_4bit (A, F);
2	input[3:0] A;
3	output[3:0] F;
4	assign F = ~ A;
5	endmodule

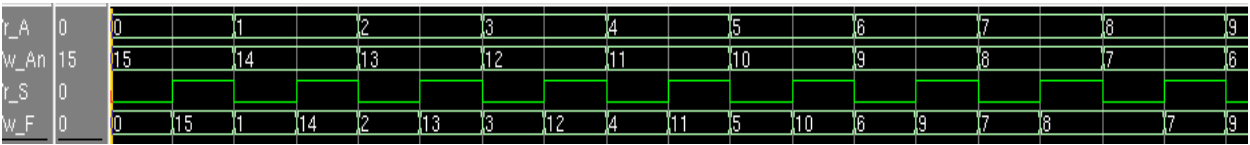
Code for Mux combination:

Ln#	
1	module Mux4_2_1 (A,B, SEL, F);
2	input[3:0] A,B;
3	input SEL;
4	output[3:0] F;
5	
6	MUX mux0(.A(A[1:0]), .B(B[1:0]), .SEL(SEL), .F(F[1:0]));
7	MUX mux1(.A(A[3:2]), .B(B[3:2]), .SEL(SEL), .F(F[3:2]));
8	
9	endmodule
10	

Test Bench:

Ln#	
1	module hw4_tb();
2	reg[3:0] A;
3	reg S;
4	wire [3:0] W, F; //w is wire connection inverters to mux, f is output
5	
6	initial
7	begin
8	A = 4'b0000;
9	S = 1'b0;
10	end
11	
12	always
13	#10 S = ~S;
14	always
15	#20 A = A+1;
16	
17	inverter_4bit inv0(.A(A), .F(W));
18	Mux4_2_1 mux0(.A(W), .B(A), .SEL(S), .F(F));
19	
20	endmodule

Waveform:



Numbers are shown in unsigned convention